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(54) **OPENING METHOD AND OPENING DEVICE**

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**ABSTRACT**

An opening method and opening device are provided. The opening device can perform opening according to the following steps: controlling a first laser processing device to process an object to be opened to form a first opening area; controlling a second laser processing device to process the object to be opened to form a second opening area; the power of the first laser processing device is greater than that of the second laser processing device, and the light spot of the first laser processing device is larger than that of the second laser processing device. The second opening area surrounds the edge of the first opening area and connects to the first opening area.

